Final Product Change Notification

202209021F01 : C90TFS LQFP80 Assembly Site Expansion from ASE-CL to TFME

Note: This notice is NXP Company Proprietary.

Issue Date: Oct 05, 2022 **Effective date:** Jan 03, 2023

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Management summary

Assembly site expansion for C90TFS parts associated with this notification from the current ASE, Chung Li, Taiwan (ASE-CL) assembly facility to TongFu Microeletronics Co.,Ltd, Nantong. China (TFME) Assembly Facility.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[X]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[X]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[ ]Wafer Fab Location	[X]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

PCN Overview
Description

NXP Semiconductors announces the Assembly site expansion for C90TFS parts associated with this notification from the current ASE, Chung Li, Taiwan (ASE-CL) assembly facility to TongFu Microeletronics Co.,Ltd, Nantong. China (TFME) Assembly Facility.

Please see attached files for additional details.

Reason

Qualification of TFME is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking
Refer to Remarks section for details

Product Availability

Sample Information

Samples are available upon request
Samples with part number PC56F84766T2VLK/PK10DX256VLK7 will be provided upon request.
Production
Planned first shipment Jan 09, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality
Disposition of Old Products
Assembly site expansion. No depletion of Inventory required.

Additional information

Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Nov 04, 2022.

Remarks

The assembly site, among other information, is reflected in the package trace code.
The format for the NXP standard trace code: AWLYYWWZ is the following:
A=Assembly Site, WL=Wafer Lot, YY=Year, WW=Work Week, Z= Assembly Split Lot.

The current assembly site marking for ASE-CL is A = X
The marking for proposed assembly site TFME is A = XN

TFME LQFP80 12x12 has two Eject Pins Dot while ASE-CL doesn't have Eject Pins Dot.
Detailed information is shown in attachment "LQFP80_12x12_visual compare.pdf"

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.
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